Time-Lag SMD Fuses 0603

multicomp PRO

RoHS Compliant



Description

The SMD fuses stand out due to their ultra-small size and excellent electrical performance, reliability and quality. The solder-free design provides outstanding on-off and temperature cycling characteristics during operation and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.

Applications

Industrial Products such as cellphones, DVD players, battery packs, hard disk drives and digital cameras

Features

- High inrush current withstanding capability
- Compatible with reflow and wave solder
- Ceramic and glass construction
- Excellent environmental integrity
- One time positive disconnect
- Lead-free and Halogen-free
- Designed compliant to UL 248-14

Specifications

Operating Temperature: -55°C to +125°CStorage Conditions: +10°C to +60°CRelative Humidity: \leq 75% yearly average without dew, maximum 30 days at 95%Vibration Resistance: 24 cycles at 15 min. each
10-60Hz at 0.75mm amplitude

60-2000Hz at 10g acceleration

Electrical Characteristics

Time vs Current Characteristics Table

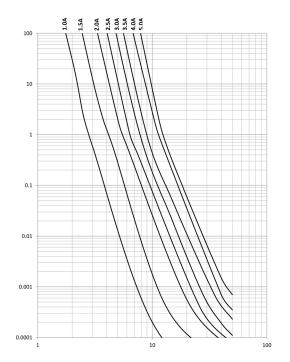
(measured with constant current power supply)

Time vs Current Characteristics					
Rated current	100%	200%	250%		
1A to 5A	>4h	1s~60s	<5s		



multicomp PRO

Average Time Current (I-T) Curves



Electrical Characteristics

Amp Code	Rated Current	Rated Voltage DC	Typical Voltage Drop (mV)	Breaking Capacity	Typical Melting I²T (A²s)	Typ. Resistance (mΩ)	Alpha Mark
1100	1A	255 150 32V DC 135 120 125	325		0.015	216~280	Н
1150	1.5A		255	50A @ 22V DC	0.05	110~180	К
1200	2A		150		0.125	60~88	Ν
1250	2.5A		135		0.14	47~61	0
1300	3A		120	50A @ 32V DC	0.35	26~44	Р
1350	3.5A		125		0.62	20~35	R
1400	4A		110		0.81	17~24	S
1500	5A		103		2	10.5~15	Т

1. DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)

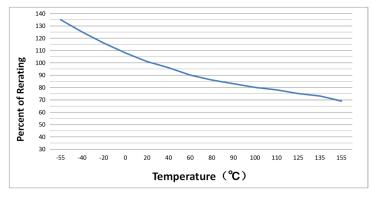
2. DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25degrees

3. Typical Pre-arcing I²t are measured at 10In Current



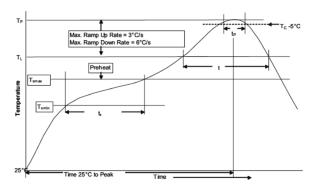
multicomp PRO

Temperature Re-rating Curve



Normal ambient temperature: $23 \pm 3^{\circ}$ COperating temperature: -55° C ~ +150°C, with proper correction factor applied

Soldering Parameters



Profile Featu	Ire	Pb-Free Assembly	
Average Ramp-UP Rate(Tsmax to Tp)		3°C/s Max.	
Preheat	Temperature Min (Ts min)	150°C	
	Temperature Max (Ts max)	200°C	
	Time (Tsmin to Ts max)	60sec to 120sec	
Liquidous temperature(TL) Time at liquidous(tL)		217°C 60 to 150S	
Peak package body temperature (Tp)		260°C	
Time (tP) within 5°C of the specified classification temperature (Tc)		30S	
Average ramp-down rate (Tp to Tsmax)		6°C/s Max.	
Time (25°C to Peak Temperature)		8 Minutes Max.	

1. Infrared Reflow:

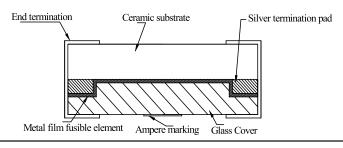
Temperature: 260°C Time: 30S

Recommend reflow profile

2. Wave Soldering: Reservoir Temperature: 260°C

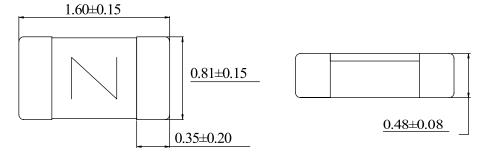
Time in Reservoir: 10sec Max.

Mechanical Specifications

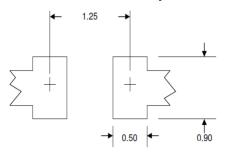




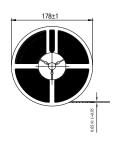
Diagram



Recommended land pattern



Packing Information



Part Number Table

Description	Part Number	
SMD Fuse, Time-Lag, 1A, 32V DC, 0603	MCCFB0603TTT/1	
SMD Fuse, Time-Lag, 1.5A, 32V DC, 0603	MCCFB0603TTT/1.5	
SMD Fuse, Time-Lag, 2.5A, 32V DC, 0603	MCCFB0603TTT/2.5	
SMD Fuse, Time-Lag, 3A, 32V DC, 0603	MCCFB0603TTT/3	
SMD Fuse, Time-Lag, 3A, 32V DC, 0603	MP001603	
SMD Fuse, Time-Lag, 4A, 32V DC, 0603	MCCFB0603TTT/4	
SMD Fuse, Time-Lag, 5A, 32V DC, 0603	MCCFB0603TTT/5	
SMD Fuse, Time-Lag, 5A, 32V DC, 0603	MP001604	

Dimensions : Millimetres

Important Notice : This data sheet and its contents (the "Information") belong to the members of the AVNET group of companies (the "Group") or are licensed to it. No licence is granted for the use of it other than for information purposes in connection with the products to which it relates. No licence of any intellectual property rights is granted. The Information is subject to change without notice and replaces all data sheets previously supplied. The Information supplied is believed to be accurate but the Group assumes no responsibility for its accuracy or completeness, any error in or omission from it or for any use made of it. Users of this data sheet should check for themselves the Information or use of it (including liability resulting from negligence or where the Group was aware of the possibility of such loss or damage arising) is excluded. This will not operate to limit or restrict the Group's liability for death or personal injury resulting from its negligence. Multicomp Pro is the registered trademark of Premier Farnell Limited 2019.

